PCN Number:	20191211003.1	**PCN Date:**	Jan. 14, 2020
Title:	Qualification of HFTF as an additional AT site for the TMUX1119DCKR		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	April 13, 2020	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of HFTF as an additional assembly site for the TMUX1119DCKR. Current assembly site and Material differences are as follows:

	Hana	HFTF
Mold Compound	SID#450179	SID#R-27

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
Hana	HNT	THA	Ayutthaya
HFTF	**HFT**	**CHN**	**Hefei**

Sample product shipping label (not actual product label)

Product Affected:

TMUX1119DCKR

TEXAS INSTRUMENTS

TI Information
Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TMUX1119DCK	QBS Package Reference: OPA1671IDCK
AC	Autoclave 121C	96 Hours	3/231/0	-
CDM	ESD - CDM	2000 V	1/3/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-
HBM	ESD - HBM	6000 V	1/3/0	-
HTOL	Life Test, 150C	300 Hours	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	-
LU	Latch-up	(Per JESD78)	1/6/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-
WBP	Bond Pull	Wires	3/228/0	-
WBS	Wire Bond Shear	Wires	3/228/0	-

- QBS: Qual By Similarity
- Qual Device TMUX1119DCK is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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